

STMP3770XXLAE3N

(Not Recommended for New Designs)

Piano 2p0 TA3 ROM Revision



Package :

[LQFP100](#)

LQFP100, plastic, low profile quad flat package; 100 terminals; 0.5 mm pitch; 14 mm x 14 mm x 1.4 mm body

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Environmental Information

Material Declaration	PbFree	EU RoHS	Halogen Free	RHF Indicator	2nd Level Interconnect	REACH SVHC	Weight (mg)
STMP3770XXLAE3N (935323032557)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	e3	REACH SVHC	650.4

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
STMP3770XXLAE3N (935323032557)	No	3	260	40

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)
STMP3770XXLAE3N (935323032557)	854231	5A992

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